

SPECIFICATIONS

CUSTOMER: _____

DESCRIPTION: Geomagnetic Antenna

CUSTOMER PART NO: _____

OUR MODEL NO: **PBX1608MA02**

DATE: 2021/09/01

PLEASE RETURN TO US ONE COPY OF “SPECIFICATION FOR APPROVAL”
WITH YOUR APPROVED SIGNATURES

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DESIGNED BY: Sera	APPROVED BY: XD			
TITLE: CHIP2450-1608 Specification		DOCUMENT NO.	1608	SPEC REV.
				P1

PBX1608MA01 Specification

Operating Temp. : -40℃~+85℃

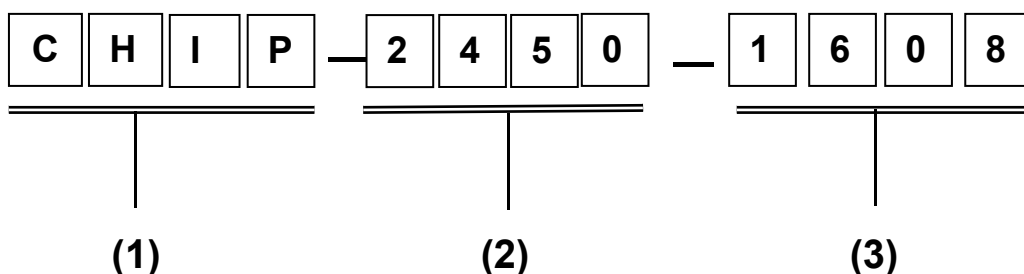
1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

2. APPLICATIONS:

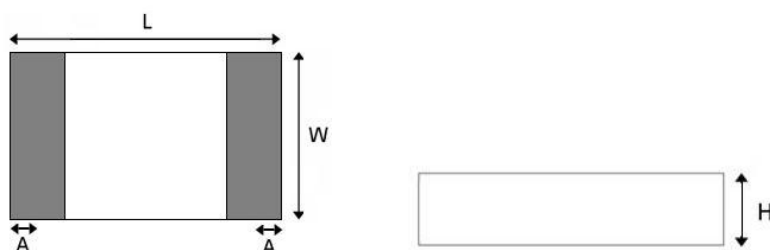
- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

3. PRODUCT IDENTIFICATION



- (1) Product type: Multilayer chip Antenna
 (2) Center Frequency: 2450MHz
 (3) External Dimensions (L×W) (mm): 1.6*0.8

4. SHAPE AND DIMENSIONS:



L	W	H	A
1.6±0.2	0.8±0.2	0.8±0.2	0.3±0.1

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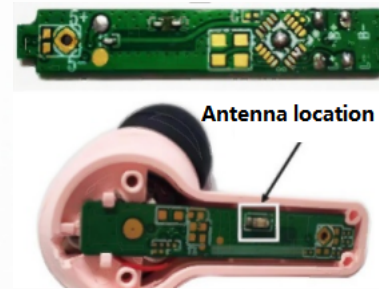
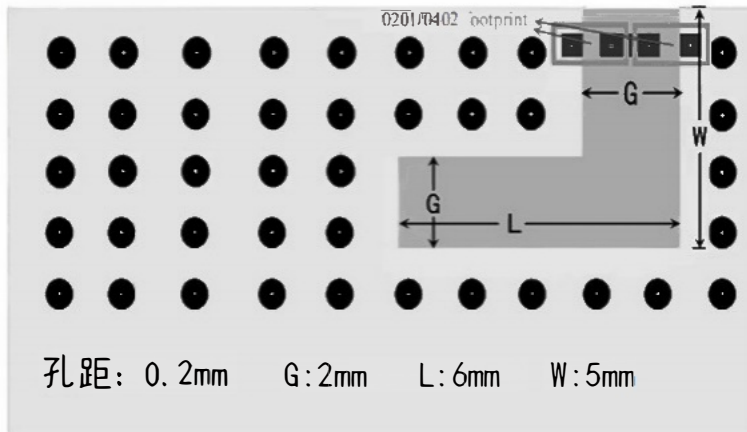
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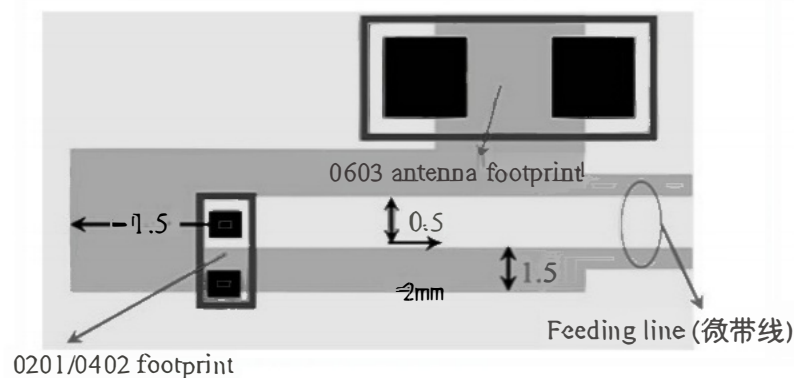
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- When the antenna is located inside or in the middle layer of the PCB (Strip-style earphones) :
(Unit: mm)

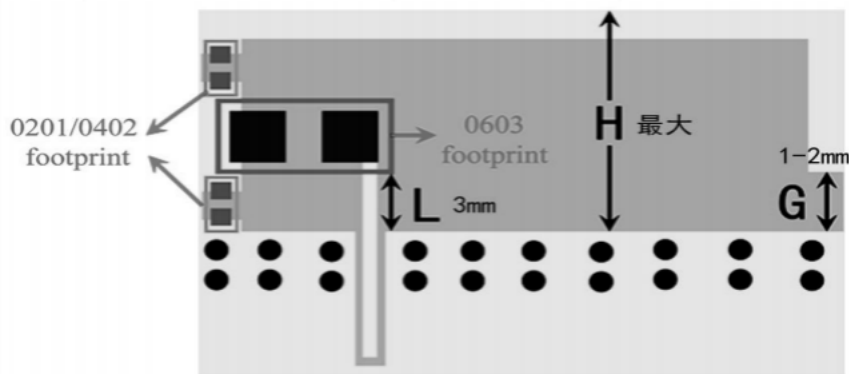


Antenna is placed out layer of PCBA



The antenna is optimally placed in the central area, with at least one row of vias required around the clearance zone.

- When the antenna is located at the edge of the PCB (in-ear earphones and some strip-style earphones):



The antenna should preferably be placed at the edge of the PCBA, with both the antenna and its routing arranged on a single layer

- The dimensions in the diagram are for reference only; actual dimensions will be optimized according to different board layouts.
- At least one row of vias (0.3mm diameter) is optimally required around the clearance zone to provide isolation from other circuits or components on the PCBA.

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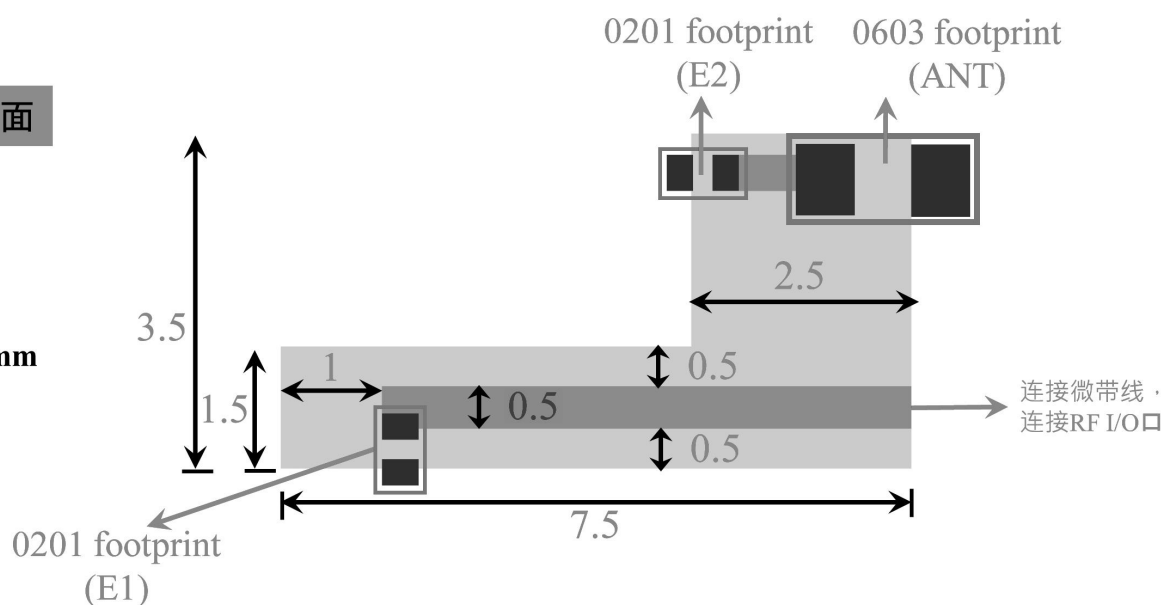
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Antenna packaging Option 1 (3.5mm×7.5mm)

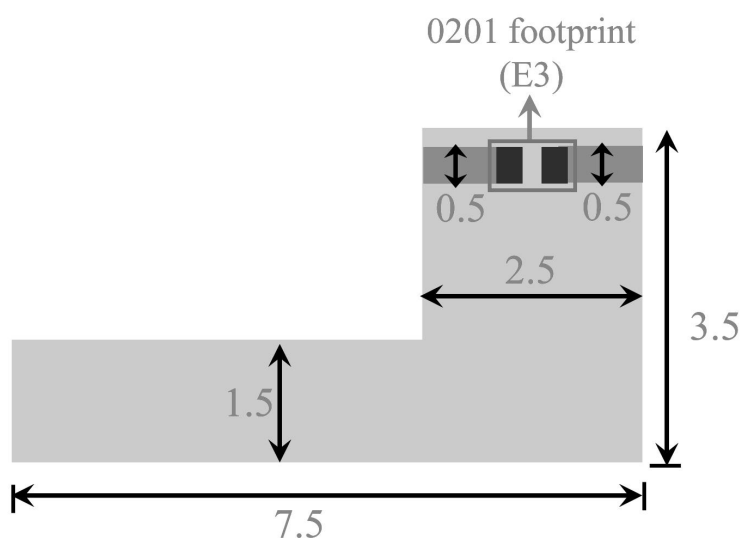
TOP面

Unit:mm

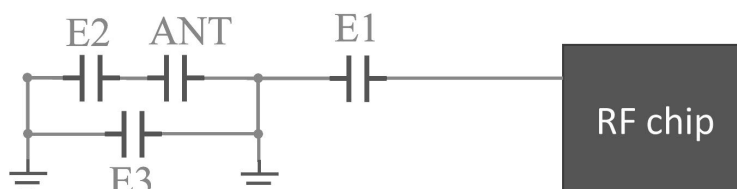


BOTTOM面

Unit:mm



原理图



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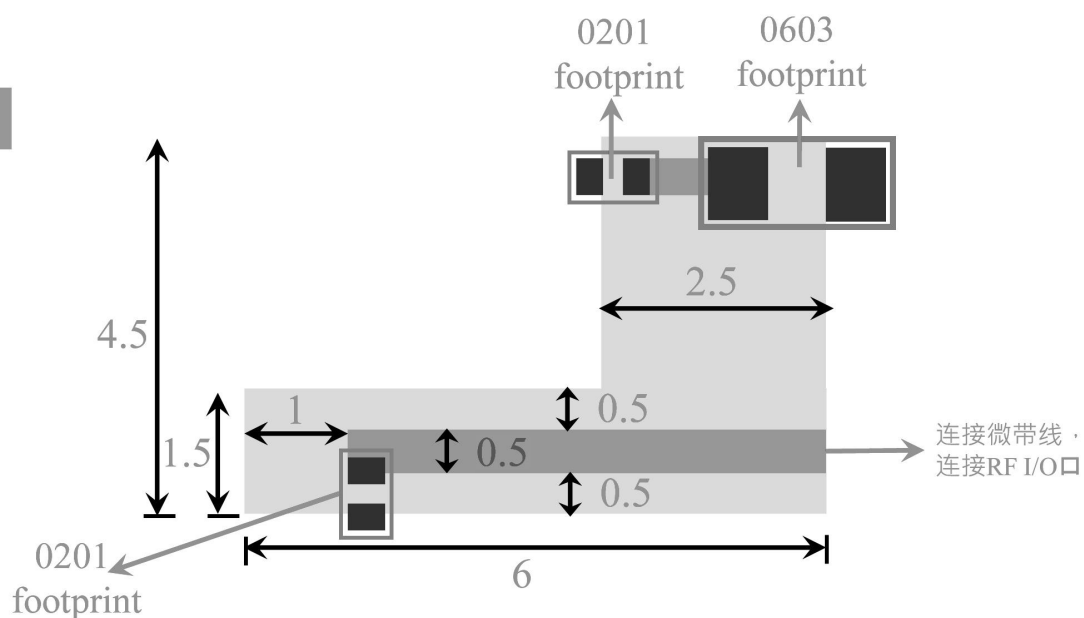
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Antenna packaging Option 2 (4.5mm×6mm)

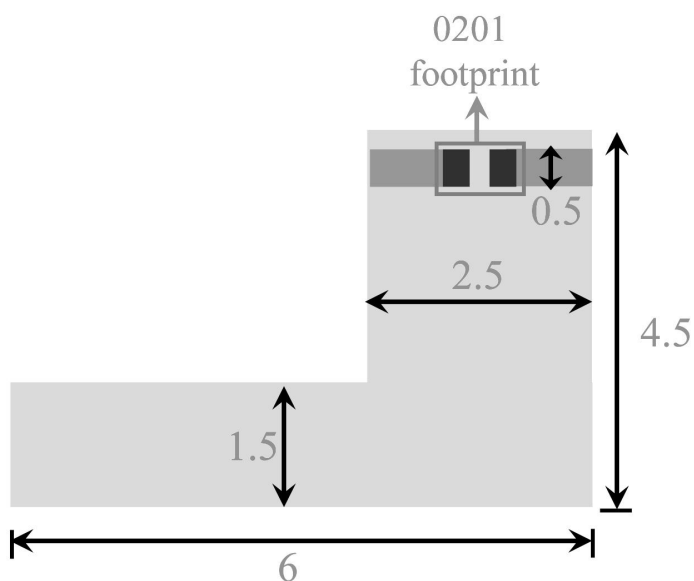
TOP面

Unit:mm



BOTTOM面

Unit:mm



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ANGLES = ±

HOLEDIA = ±



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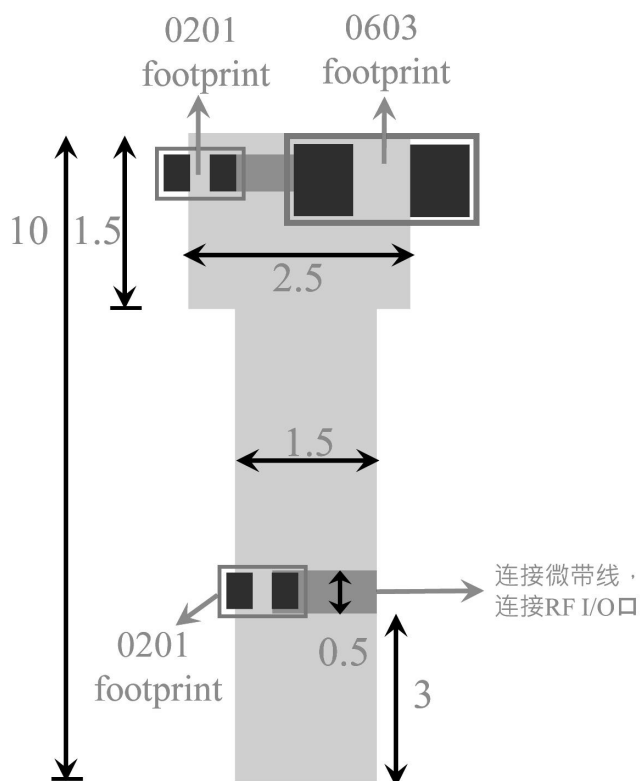
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Antenna packaging Option 3 (1.5mm×10mm)

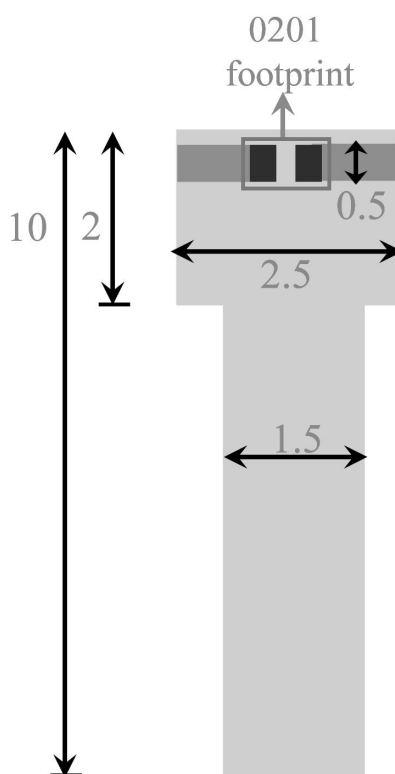
TOP面

Unit:mm



BOTTOM面

Unit:mm



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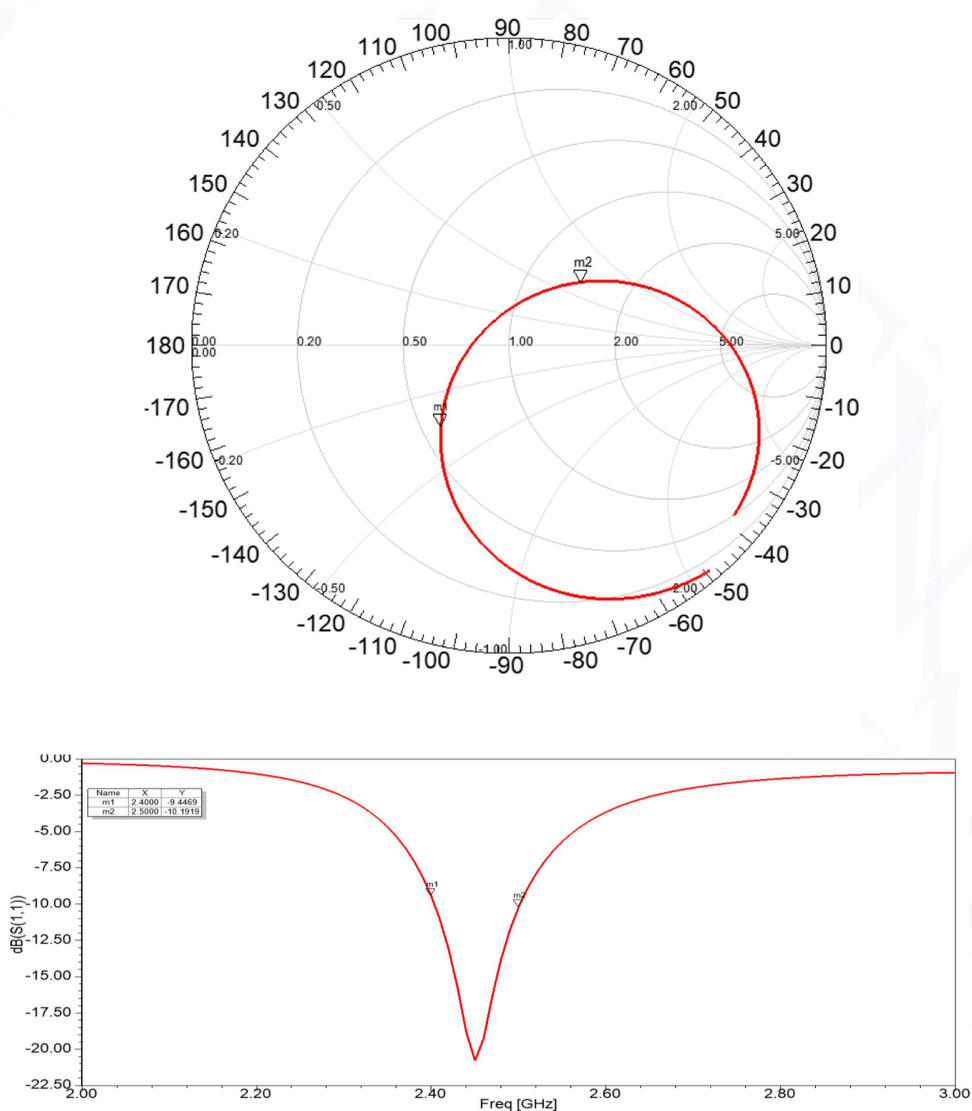
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Electrical Characteristics

	Feature	Specification
1	Central frequency	2.45GHz&5.5GHz
2	Bandwidth	>100MHz
3	Peak gain	>3dBi
4	VSWR	<2
5	Polarization	Linear
6	Azimuth beamwidth	Omnidirectional
7	Impedance	50 Ω

Characteristic Curves



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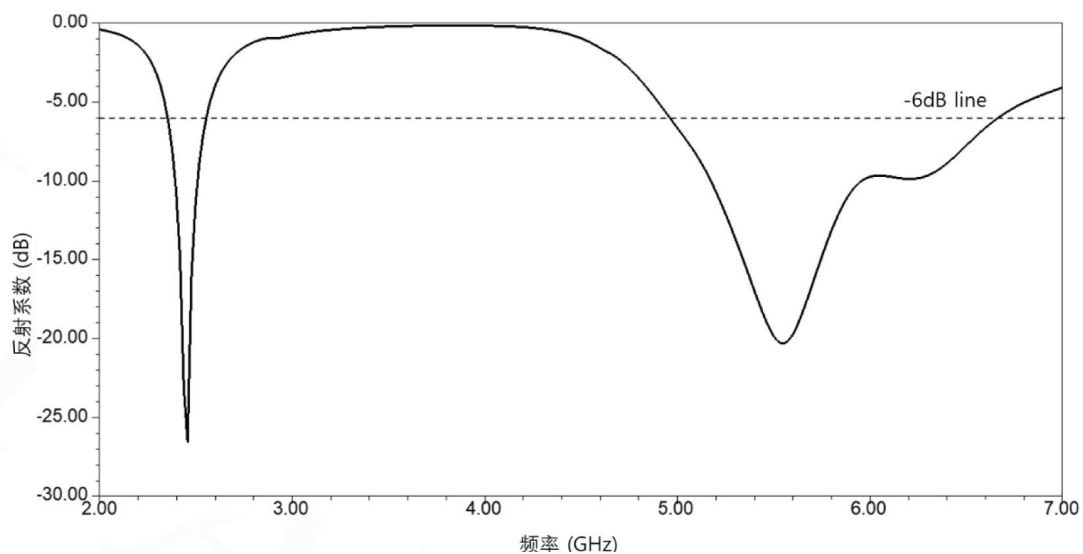
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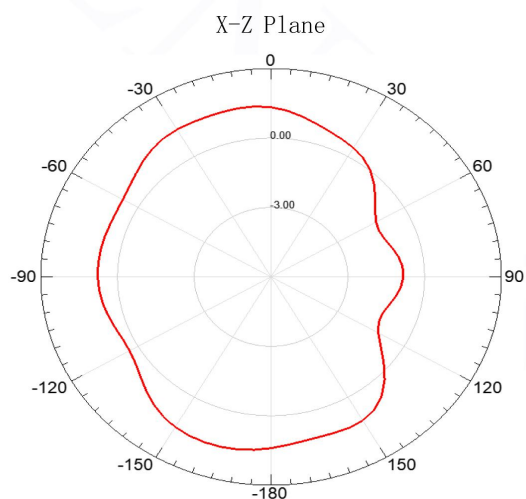
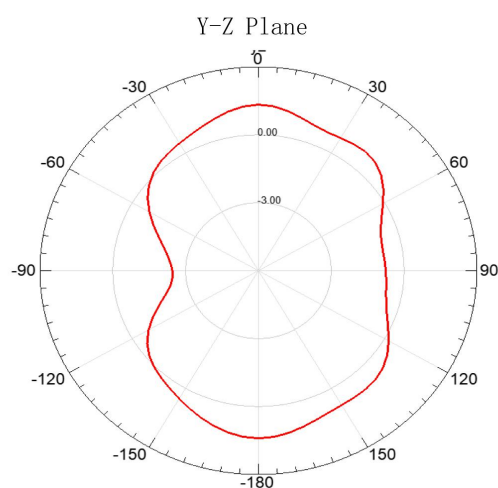
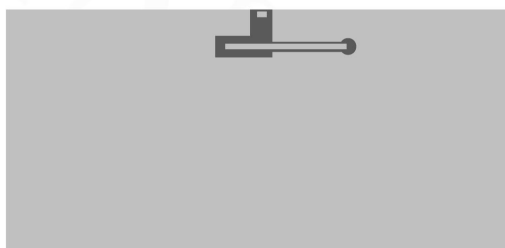
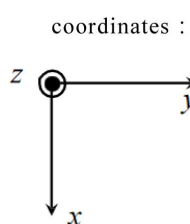
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Radiation Pattern



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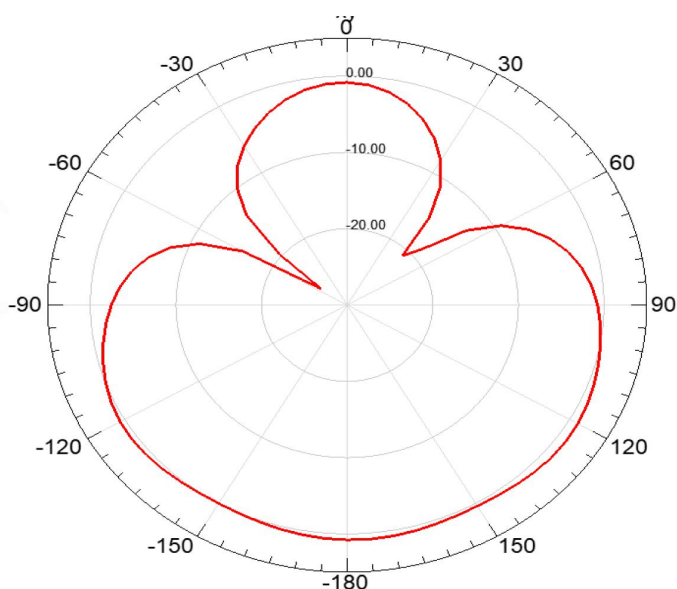
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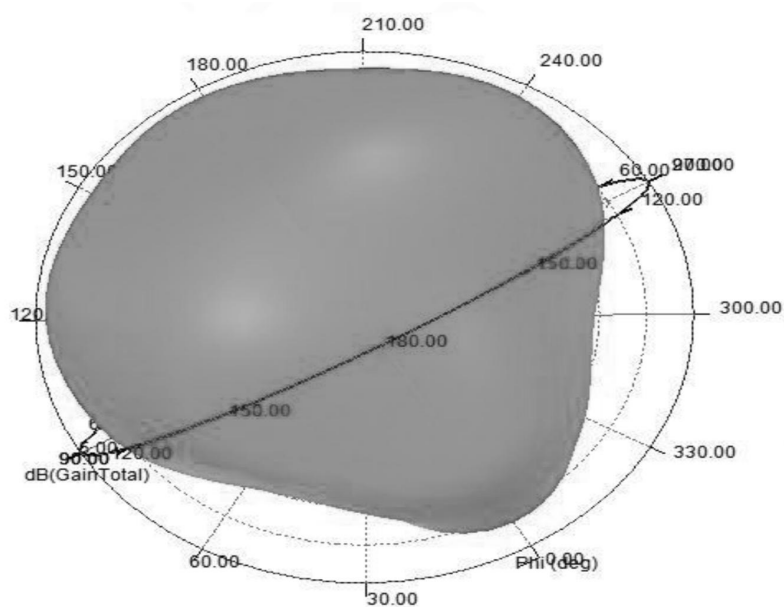
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3D Radiation Pattern



Frequency	2450MHz	5500MHz
Avg. gain	-0.85	-1.30
Peak gain	3.0	3.5
Efficiency	82%	78%

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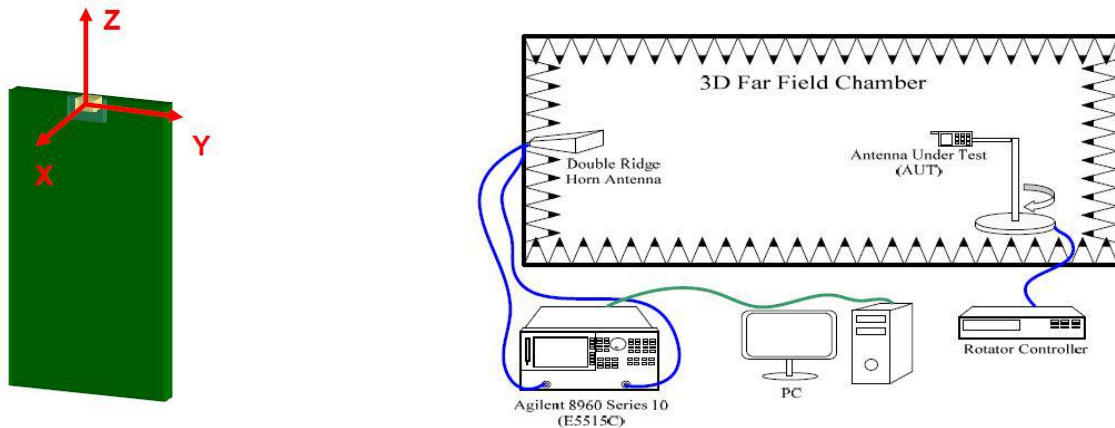
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Radiation Pattern

The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.



Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30±3 minutes at -40° C±5° C, 2. Convert to +105° C (5 minutes) 3. 30±3 minutes at +105° C±5° C, 4. Convert to -40° C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: 85±5° C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: 150° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: -40° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : 260±5°C 2. Bathing time: 10±1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of 245±5°C for 3±1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within 0 ~ 30°C and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(b) On board:

The temperature should be within -40~85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40°C to +105°C.

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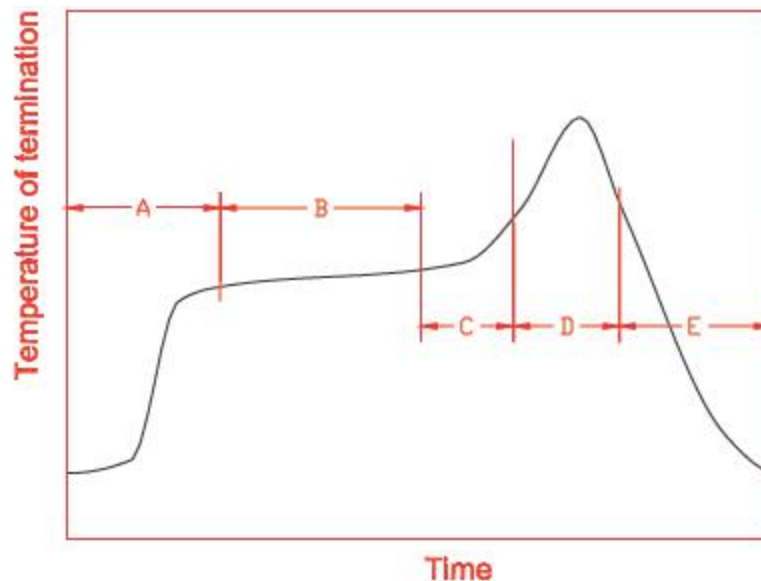
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8. Recommended Reflow Soldering



A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
B	Preheating	140°C to 160°C	60s to 120s
C	2 nd rising temperature	Preheating to 200°C	20s to 40s
D	Main heating	if 220°C	50s~60s
		if 230°C	40s~50s
		if 240°C	30s~40s
		if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s

*reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

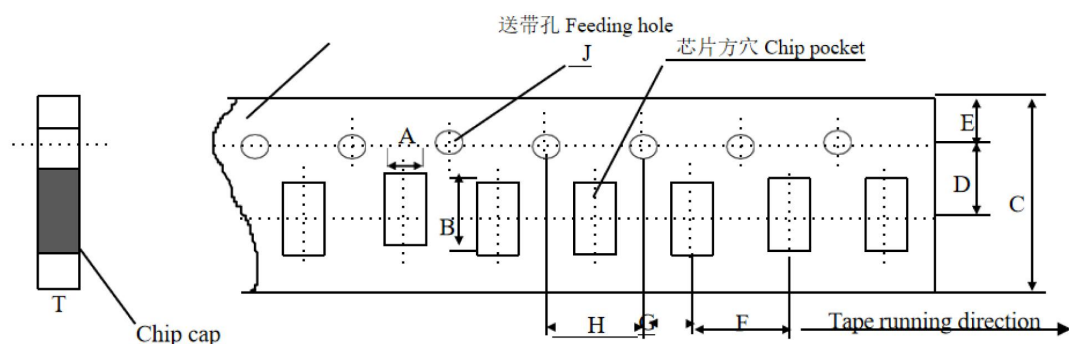
- (a) The tip temperature must be less than 350° C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

Note that excess of soldering volume will easily get crack the body of this product.

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Dimensions of paper taping:

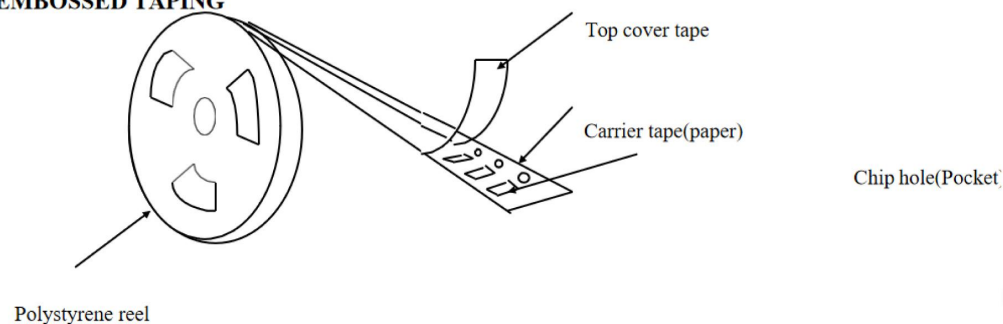


Unit: mm

代号 Code 纸带规格 papersize	A	B	C	D*	E	F	G*	H	J	T
尺寸	1.10 ±0.10	1.90 ±0.10	8.00 ±0.10	3.50 ±0.05	1.75 ±0.10	4.00 ±0.10	2.00 ±0.10	4.00 ±0.10	1.50 -0/+0.10	1.10 Max

Reel (4000 pcs/Reel)

EMBOSED TAPING



Storage Period

The guaranteed period for solderability is 6 months (Under deliver package condition).
Temperature: 5~40°C /Relative Humidity: 20~70%

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